

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

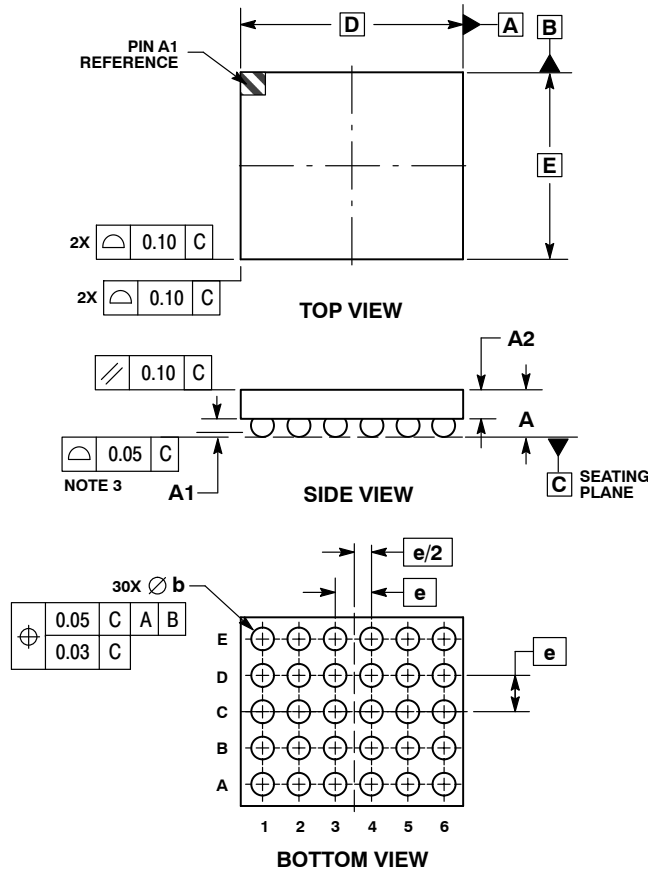
ON Semiconductor®



SCALE 4:1

WLCSP30, 2.46x2.06
CASE 567CU-01
ISSUE A

DATE 30 JUN 2011

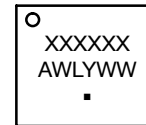


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.33	0.39
b	0.24	0.29
D	2.46 BSC	
E	2.06 BSC	
e	0.40 BSC	

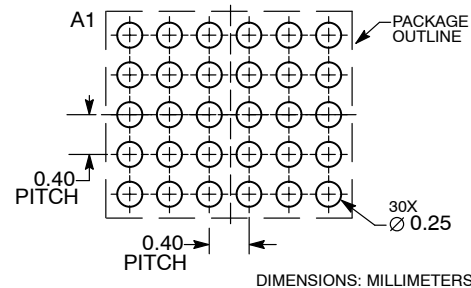
GENERIC MARKING DIAGRAM*



- XXXXXX= Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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